

# HY1607AP-VB Datasheet N-Channel 60 V (D-S) MOSFET

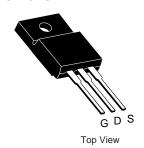
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>			
60	0.005 at V <sub>GS</sub> = 10 V	120			
00	$0.013$ at $V_{GS} = 4.5 \text{ V}$	95			

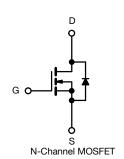
#### **FEATURES**

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:









ABSOLUTE MAXIMUM RATINGS ( $T_C =$	25 °C, unless othe	rwise noted)		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		$V_{GS}$	± 20	V
Continuous Dunin Courset /T 475 90\b	T <sub>C</sub> = 25 °C		120	
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 100 °C	I <sub>D</sub>	95 <sup>a</sup>	
Pulsed Drain Current		I <sub>DM</sub>	300	А
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	70 <sup>a</sup>	1
Avalanche Current		I <sub>AS</sub>	I <sub>AS</sub> 50	
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ
Mayimum Dayar Dissination	T <sub>C</sub> = 25 °C	136	W	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3 <sup>b</sup> , 8.3 <sup>b, c</sup>	vv
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 10 sec	$R_{thJA}$	15	18	
waximum Junction-to-Ambient*	Steady State	'`thJA	40	50	°C/W
Maximum Junction-to-Case		$R_{thJC}$	0.85	1.1	

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c.\ t \leq 10\ s.$



Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static			L				
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2	3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		50		μΑ	
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250	1	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	60			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.005		A Ω S	
D : 0	D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.010		0	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 175 ^{\circ}\text{C}$		0.015		22	
		$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.013			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$		60		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>			5650			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		1120		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			525			
Total Gate Charge <sup>c</sup>	Qg			47	70		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		10		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20	S pF	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, R_{L} = 0.6 \Omega$		15	25		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D\cong 50$ A, $V_{GEN}$ = 10 V, $R_g$ = 2.5 $\Omega$		35	50	ris	
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)		•			
Pulsed Current	I <sub>SM</sub>			300		Α	
Diode Forward Voltage	$V_{SD}$	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		1	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs		45	100	ns	

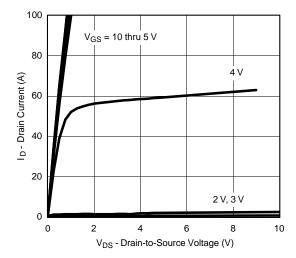
#### Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- c. Independent of operating temperature.

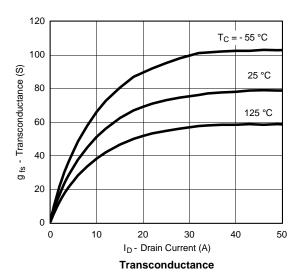
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



### TYPICAL CHARACTERISTICS (25 °C unless noted)



#### **Output Characteristics**



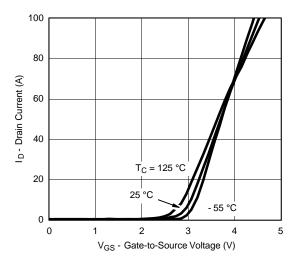
## 7000 6000 Ciss 5000 0 2000 1000 Crss

 $V_{DS}$  - Drain-to-Source Voltage (V)  $\label{eq:capacitance}$ 

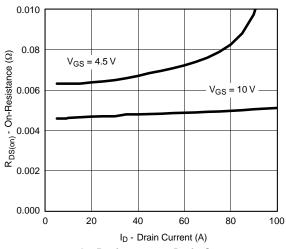
30

50

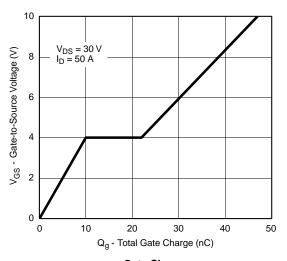
60



#### **Transfer Characteristics**



On-Resistance vs. Drain Current



**Gate Charge** 

服务热线:400-655-8788

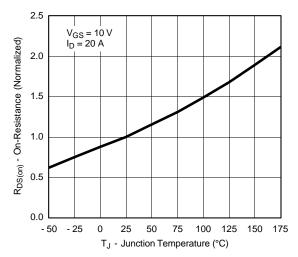
10

0

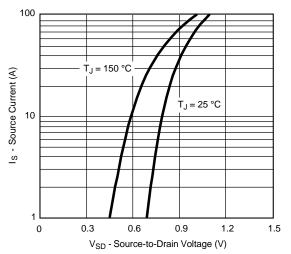
8000



### TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

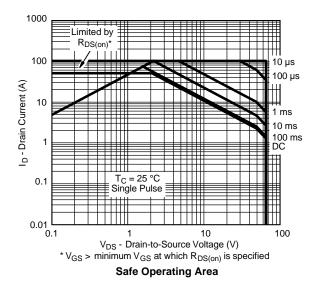


Source-Drain Diode Forward Voltage

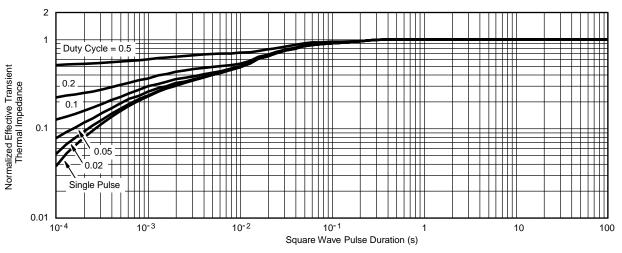


#### THERMAL RATINGS





Maximum Drain Current vs. Ambient Temperature



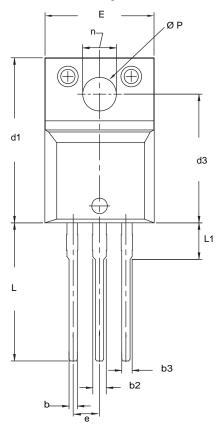
Normalized Thermal Transient Impedance, Junction-to-Case

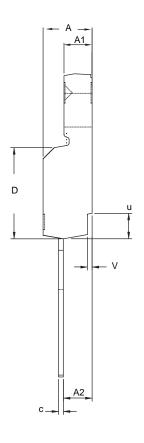
服务热线:400-655-8788

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#### **TO-220 FULLPAK (HIGH VOLTAGE)**





DIM.	MILLIF	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.		
Α	4.570	4.830	0.180	0.190		
A1	2.570	2.830	0.101	0.111		
A2	2.510	2.850	0.099	0.112		
b	0.622	0.890	0.024	0.035		
b2	1.229	1.400	0.048	0.055		
b3	1.229	1.400	0.048	0.055		
С	0.440	0.629	0.017	0.025		
D	8.650	9.800	0.341	0.386		
d1	15.88	16.120	0.622	0.635		
d3	12.300	12.920	0.484	0.509		
E	10.360	10.630	0.408	0.419		
е	2.54	BSC	0.100 BSC			
L	13.200	13.730	0.520	0.541		
L1	3.100	3.500	0.122	0.138		
n	6.050	6.150	0.238	0.242		
ØΡ	3.050	3.450	0.120	0.136		
u	2.400	2.500	0.094	0.098		
٧	0.400	0.500	0.016	0.020		

- To be used only for process drawing.
  These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
  All critical dimensions should C meet C<sub>pk</sub> > 1.33.
  All dimensions include burrs and plating thickness.
  No chipping or package damage.



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